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Electronic Version 1.0.3

Stylesheet Version: 1.0

Attorney Docket
Number:

BUR920010100

Submission Type: Utility
Patent Filing

METHOD OF CONNECTING CORE I/O PINS TO BACKSIDE CHIP I/O PADS

First Named Inventor: Joseph Iadanza

SUBMITTED BY

Name: Mr. Richard A. Henkler Esq.

Registration Number: 39,220

Electronic Signature Mark: Richard
A. Henkler /s/

Date Signed: 20020226

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I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.

Attached Files:

declaration	01-0100_Declaration.1.tif
declaration	01-0100_Declaration.2.tif
declaration	01-0100_Declaration.3.tif
bid-transmittal	BUR920010100US1 apds.xml

BUR920010100US1.xml
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Comments:

Assignee: International Business Machines Corporation Assignee Address: Armonk, NY 10504

2025-06-26 14:28:00

Docket No.
BUR920010100U

Declaration and Power of Attorney For Patent Application

English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and in which a patent is sought on the invention entitled
METHOD OF CONNECTING CORE I/O PINS TO BACKSIDE CHIP I/O PADS

the specification of which

(check one)

☒ is attached hereto.

☐ was filed on _____ as United States Application No. or PCT International
Application Number _____
and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulation Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) Section 365(b) of any foreign application(s) for patent or inventor's certificate, or Section 365(a) any PCT International application which designated at least one country other than the United States listed below and have also identified below, by checking the box, any foreign application for patent inventor's certificate or PCT International application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)

Priority Not Claimed

(Number)

(Country)

(Day/Month/Year Filed)

☐

(Number)

(Country)

(Day/Month/Year Filed)

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I hereby claim the benefit under 35 U.S.C. Section 119(e) of any United States provision: application(s) listed below:

(Application Serial No.)	(Filing Date)
(Application Serial No.)	(Filing Date)
(Application Serial No.)	(Filing Date)

I hereby claim the benefit under 35 U. S. C. Section 120 of any United States application(s), or Section 365(c) of any PCT International application designating the United States, listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. Section 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, C. F. R. Section 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/ agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (list name and registration number)

Mark F. Chadurjian-30,739

Joseph C. Redmond, Jr.-18,753

Richard A. Henkler-39,220

all attorneys and/or agents at Customer No. 30449

Richard M. Kotulak-27,712

James M. Leas-34,372

William D. Sabo-27,465

Robert A. Walsh-26,516

Howard J. Walter, Jr.-24,832

Christopher A. Hughes-26,914

Stanley B. Green-24,351

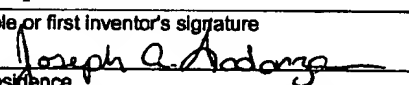
John E. Hoel-26,279

Send Correspondence to:

Customer No. 30449

Direct Telephone Calls to: (name and telephone number)

Jack P. Friedman - (518) 220-1850

Full name of sole or first inventor	
Joseph A. Iadanza	
Sole or first inventor's signature	Date
	2/22/2002
Residence	
160 Billings Farm Road, Hinesburg, VT 05461	
Citizenship	
USA	
Post Office Address	
Same as Residence	

Full name of second inventor, if any	
Second inventor's signature	Date
Residence	
Citizenship	
Post Office Address	